

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,767,846 B2
DATED : July 27, 2004
INVENTOR(S) : Stanislaw Kopacz et al.

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page.

Item [57], **ABSTRACT**,

Line 9, reads "...support member and an ramp that is inclined such that the..." and should read -- ...support member and a ramp that is inclined such that the... --.

Drawings.

Figure 6, reads "158" and should be --150 --.

Column 1.

Line 14, reads "...and, in particular, to a methods for a securing a substrate..." and should read -- ... and, in particular, to a method for securing a substrate... --.

Lines 51-52, reads "... rollers of the latches roll or slide over the rim of the wafer As the latches move to a latched position, excessive latching..." and should read -- ... rollers of the latches roll or slide over the rim of the wafer. As the latches move to a latched position, excessive latching... --.

Column 2.

Lines 57-59, reads "...inner peripheral flange when the latch body is in the latched position. (new paragraph) The clamping roller assembly has a resiliently-biased..." and should read -- ...inner peripheral flange when the latch body is in the latched position. The clamping roller assembly has a resiliently-biased... --. (no new paragraph)

Column 3.

Line 22, reads "... member and an ramp that is inclined such that the clamping..." and should read -- ... member and a ramp that is inclined such that the clamping... --.

Lines 37-38, reads "... the second surface in the effective to secure the substrate against the substrate-engaging surface." and should read -- ... the second surface effective to secure the substrate against the substrate-engaging surface. --

Column 6.

Lines 12-13, reads "... arm (not shown) is inserting wafer 12 into, or removing wafer 12, from wafer holder 10. The construction and..." and should read -- ... arm (not shown) is inserting wafer 12 into, or removing wafer 12 from, wafer holder 10. The construction and... --.

Column 8.

Line 9, reads "... the open end 78, rolling element 82 and a compression..." and should read -- ... the open end 78. Rolling element 82 and a compression... --.

Line 11, reads "...cylindrical surface to 80 of sleeve 74 is dimensioned and ..." and should read -- ... cylindrical surface 80 of sleeve 74 is dimensioned and... --.

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Column 12.

Lines 5-6, reads "... wafer 12. The clamp ring 100 is provided with a plurality of an upwardly-facing circular recesses, of which circular..." and should read -- ... wafer 12. The clamp ring 100 is provided with a plurality of upwardly-facing circular recesses, of which circular... --.

Column 13.

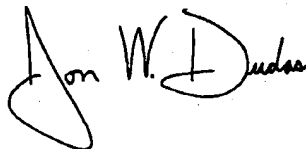
Line 34, reads "... about 90° from cusped indent 148. Headed cylindrical..." and should read -- ... about 90° from cusped detent 148. Headed cylindrical... --.

Line 40, reads "... 118, with the supporting roller assembly 28 rolling engaged..." and should read -- ... 118, with the supporting roller assembly 28 rollingly engaged... --.

Line 58, reads "... 28 rolling engaged with the bottom surface 108 and transversing ..." and should read -- ... 28 rollingly engaged with the bottom surface 108 and trasversing... --.

Signed and Sealed this

Thirtieth Day of August, 2005



JON W. DUDAS
Director of the United States Patent and Trademark Office